

**N-Ch MOSFET** 

#### **General Description**

The WSC50N03 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSC50N03 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge •
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

#### **Absolute Maximum Ratings**

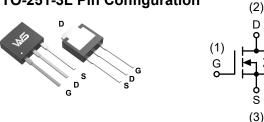
#### **Product Summery**

BVDSS	RDSON	ID
30V	10mΩ	43A

#### Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### **TO-251-3L Pin Configuration**



Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	43	А
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	A
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	11	A
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	9	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	112	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	53	mJ
I <sub>AS</sub>	Avalanche Current	22	А
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	37.5	W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C

#### **Thermal Data**

Symbol	Parameter		Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		4	°C/W



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#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
∆BV <sub>DSS</sub> /∆T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.0193		V/℃	
Б	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		10	12		
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		15	18	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2	1.5	2.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , I <sub>D</sub> =250uA		-3.97		mV/°C	
	Drain Source Lookage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		34		S	
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.8	3.6	Ω	
Qg	Total Gate Charge (4.5V)			9.8	13.7		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =15V , $V_{GS}$ =4.5V , $I_{D}$ =15A		4.2	5.88	nC	
Q <sub>gd</sub>	Gate-Drain Charge			3.6	5.0		
T <sub>d(on)</sub>	Turn-On Delay Time			5	8.0		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		8	14		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =15A		4	8	ns	
T <sub>f</sub>	Fall Time			31	62		
C <sub>iss</sub>	Input Capacitance			940	1316		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		131	183	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			109	153		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =15A	24.6			mJ

### **Diode Characteristics**

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>				15	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			112	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1	V
t <sub>rr</sub>	Reverse Recovery Time			8.5		nS
Qrr	Reverse Recovery Charge	l⊧=30A , dl/dt=100A/μs , Tյ=25℃		2.2		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10 sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}$ =25V, $V_{\text{GS}}$ =10V,L=0.1mH,I<sub>AS</sub>=15A

4.The power dissipation is limited by 175  $^\circ\!\!\!\mathrm{C}$  junction temperature

5.The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



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### **Typical Characteristics**

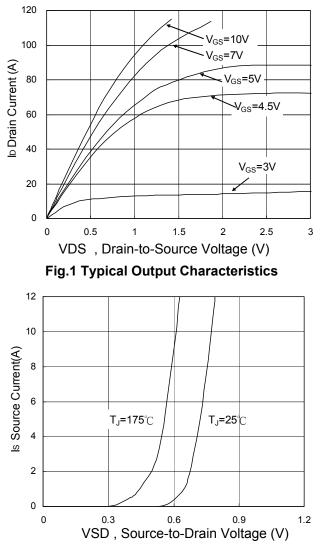
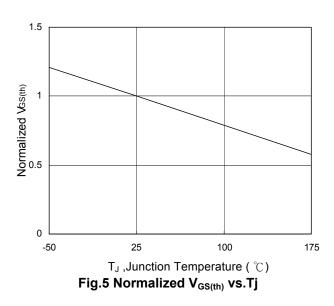


Fig.3 Forward Characteristics of Reverse



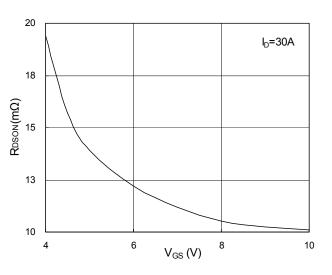
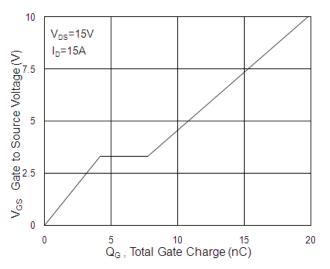
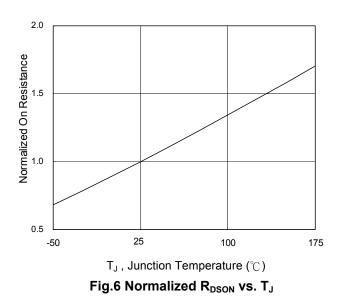


Fig.2 On-Resistance vs. G-S Voltage



**Fig.4 Gate-Charge Characteristics** 





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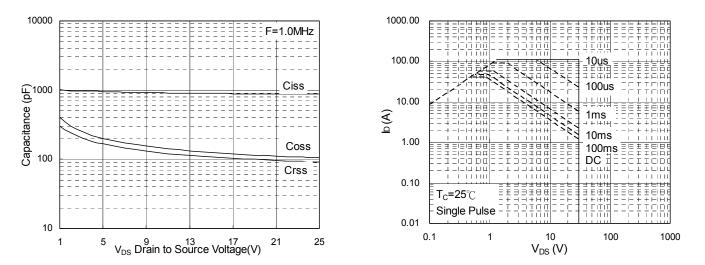
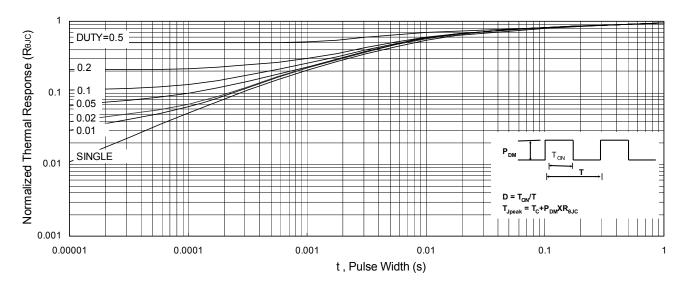
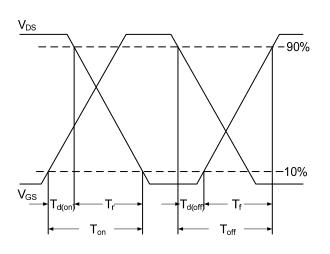


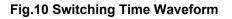
Fig.7 Capacitance

Fig.8 Safe Operating Area









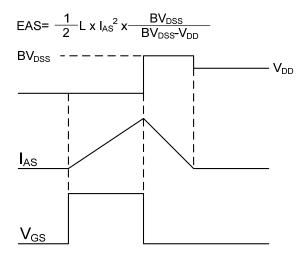


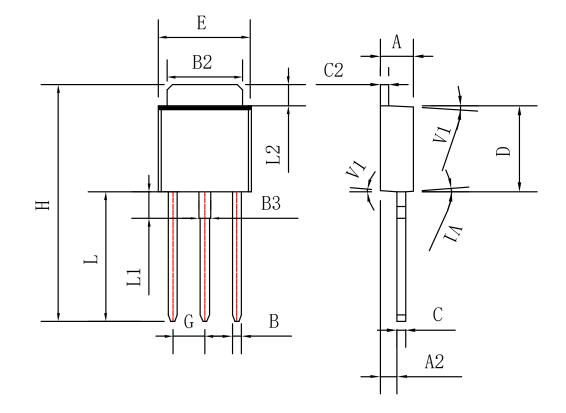
Fig.11 Unclamped Inductive Switching Waveform



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## **Packaging information**



OVMDOL	MILLIMETERS		INC	HES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	
A	2.20	2.40	0.086	0.095	
A2	0.90	1.20	0.035	0.047	
В	0.55	0.65	0.022	0.026	
B2	5.10	5.40	0.200	0.213	
B3	0.76	0.85	0.030	0.033	
С	0.45	0.62	0.018	0.024	
C2	0.48	0.62	0.019	0.024	
D	6.00	6.20	0.236	0.244	
E	6.40	6.70	0.252	0.264	
G	2.30 TYP		0.091	TYP	
Н	16.0	17.0	0.630	0.669	
L	8.90	9.40	0.350	0.370	
L1	1.80	1.90	0.071	0.075	
L2	1.37	1.50	0.054	0.059	
V1	4	ŀ	4°		



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